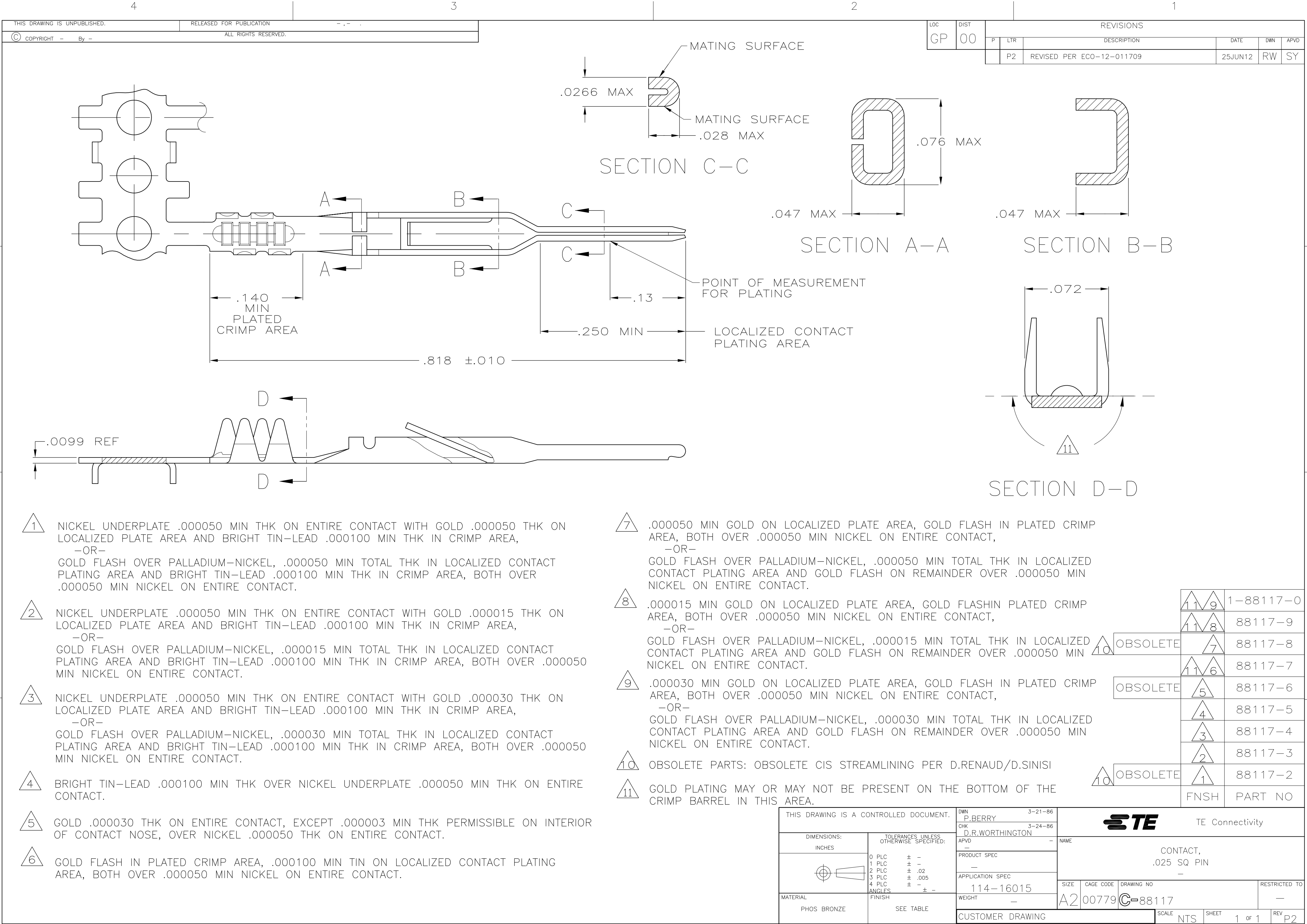




- 1 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000050 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 2 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000015 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 3 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000030 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 4 BRIGHT TIN-LEAD .000100 MIN THK OVER NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT.
- 5 GOLD .000030 THK ON ENTIRE CONTACT, EXCEPT .000003 MIN THK PERMISSIBLE ON INTERIOR OF CONTACT NOSE, OVER NICKEL .000050 THK ON ENTIRE CONTACT.
- 6 GOLD FLASH IN PLATED CRIMP AREA, .000100 MIN TIN ON LOCALIZED CONTACT PLATING AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.

- 7 .000050 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 8 .000015 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 9 .000030 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 10 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- 11 GOLD PLATING MAY OR MAY NOT BE PRESENT ON THE BOTTOM OF THE CRIMP BARREL IN THIS AREA.

		11 9	1-88117-0
		11 8	88117-9
10	OBSOLETE	7	88117-8
		11 6	88117-7
P	OBSOLETE	5	88117-6
		4	88117-5
		3	88117-4
		2	88117-3
10	OBSOLETE	1	88117-2
		FNSH	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN P.BERRY 3-21-86	TE Connectivity			
DIMENSIONS: INCHES		CHK D.R.WORTHINGTON 3-24-86				
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± .02 3 PLC ± .005 4 PLC ± - ANGLES ± - FINISH SEE TABLE		APVD - PRODUCT SPEC - APPLICATION SPEC 114-16015	NAME CONTACT, .025 SQ PIN -			
MATERIAL PHOS BRONZE		WEIGHT -	SIZE A2	CAGE CODE 00779	DRAWING NO C=88117	RESTRICTED TO -
CUSTOMER DRAWING			SCALE NTS	SHEET 1 of 1	REV P2	

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